



RELIABILITY REPORT
FOR
MAX9384EWP+
PLASTIC ENCAPSULATED DEVICES

October 23, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
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Approved by
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Conclusion

The MAX9384EWP+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX9384 fully differential dual 2:1 multiplexer (mux) features extremely low propagation delay (560ps max) and output-to-output skew (40ps max). The device is ideal for clock and data multiplexing applications. The two 2:1 muxes are controlled individually or simultaneously through mux select inputs COM_SEL, SEL0, and SEL1. The mux select inputs are compatible with ECL/PECL logic, and are referenced to on-chip outputs VBB0 and VBB1, nominally VCC - 1.33V. The differential inputs D, D-bar can be configured to accept a single-ended signal when the unused complementary input is connected to the on-chip supply output VBB as a reference voltage. All the differential inputs have bias and clamp circuits that force the outputs to a low default when the inputs are left open or at VEE. The single-ended mux select inputs have pulldowns to VEE, providing low default inputs when the select inputs are left open. The device operates with a wide supply range (VCC - VEE) of +3.0V to +5.5V for PECL or -3.0V to -5.5V for ECL, and is pin compatible with the MC100LVEL56 and MC100EL56. The MAX9384 is offered in a 20-pin wide SO package, and is specified for operation from -40°C to +85°C.

II. Manufacturing Information

A. Description/Function:	ECL/PECL Dual Differential 2:1 Multiplexer
B. Process:	GST2
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines
F. Date of Initial Production:	July 27, 2002

III. Packaging Information

A. Package Type:	20-pin SOIC (W)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-3601-0044
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	100°C/W
K. Single Layer Theta Jc:	20°C/W

IV. Die Information

A. Dimensions:	47 X 73 mils
B. Passivation:	Si ₃ N ₄ (Silicon nitride)
C. Interconnect:	Au
D. Backside Metallization:	None
E. Minimum Metal Width:	2 microns (as drawn)
F. Minimum Metal Spacing:	2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.4 \times 10^{-9}$$

$$\lambda = 22.4 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the GST2 Process results in a FIT Rate of 0.06 @ 25C and 1.10 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The EC29 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX9384EWP+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data